

Electronic Patent Application Fee Transmittal

Application Number:	10807417
Filing Date:	23-Mar-2004
Title of Invention:	Microcap wafer bonding apparatus
First Named Inventor/Applicant Name:	R. Shane Fazzio
Filer:	Thomas F. Woods
Attorney Docket Number:	10030899-1

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Notice of appeal	1401	1	540	540
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				540